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I.S. EN 62769-4:2015

Field Device Integration (FDI) - Part 4: FDI Packages

I.S. EN 62769-4:2015

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**Field Device Integration (FDI) - Part 4: FDI Packages
(IEC 62769-4:2015)**

Intégration des appareils de terrain (FDI) - Partie 4:
Paquetages FDI
(IEC 62769-4:2015)

Feldgeräteintegration (FDI) - Teil 4: FDI-Packages
(IEC 62769-4:2015)

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Comité Européen de Normalisation Electrotechnique
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EN 62769-4:2015

European foreword

The text of document 65E/347/CDV, future edition 1 of IEC 62769-4, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62769-4:2015.

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IEC 61784-1	NOTE	Harmonized as EN 61784-1.
IEC 61784-2	NOTE	Harmonized as EN 61784-2.
IEC 61804-5	NOTE	Harmonized as EN 61804-5.
IEC 62591	NOTE	Harmonized as EN 62591.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

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<u>Publication</u>	<u>Year</u> series	<u>Title</u>	<u>EN/HD</u>	<u>Year</u> series
IEC 61804		Function Blocks (FB) for process control	EN 61804	
IEC 61804-3	-	Function blocks (FB) for process control and EDDL - Part 3: EDDL specification and communication profiles	-	-
IEC 61804-4	-	Function blocks (FB) for process control -- Part 4: EDD interpretation	-	-
IEC 62769-1	-	Devices and integration in enterprise systems; Field Device Integration - Part 1: Overview	-	-
IEC 62769-5	-	Devices and integration in enterprise systems; Field Device Integration - Part 5: FDI Information Model	-	-
IEC 62769-6	-	Devices and integration in enterprise systems; Field Device Integration - Part6: Technology Mapping	-	-
IEC 62769-7	-	Devices and integration in enterprise systems; Field Device Integration - Part 7: Communication Devices	-	-
ISO 639-1	-	Codes for the representation of names of languages - Part 1: Alpha-2 code	-	-
ISO 32000-1	-	Document management_- Portable document format_- Part_1: PDF_1.7	-	-
ISO/IEC 11578	-	Information technology - Open Systems Interconnection - Remote Procedure Call (RPC)	-	-
ISO/IEC 29500-2	2012		-	-
W3C XML 1.1	-	Extensible Markup Language (XML) 1.1	-	-
XML 1.0	-	Extensible Markup Language, W3C Recommendation	-	-

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NORME INTERNATIONALE



**Field Device Integration (FDI) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI**





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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field Device Integration (FDI) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI**

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FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

The text of this standard is based on the following documents:

CDV	Report on voting
65E/347/CDV	65E/424/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents concerning

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- b) method and device for accessing a functional module of automation system, see Patent Family EP2182418;
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FIELD DEVICE INTEGRATION (FDI) – Part 4: FDI Packages

1 Scope

This part of IEC 62769 specifies the FDI Packages. The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

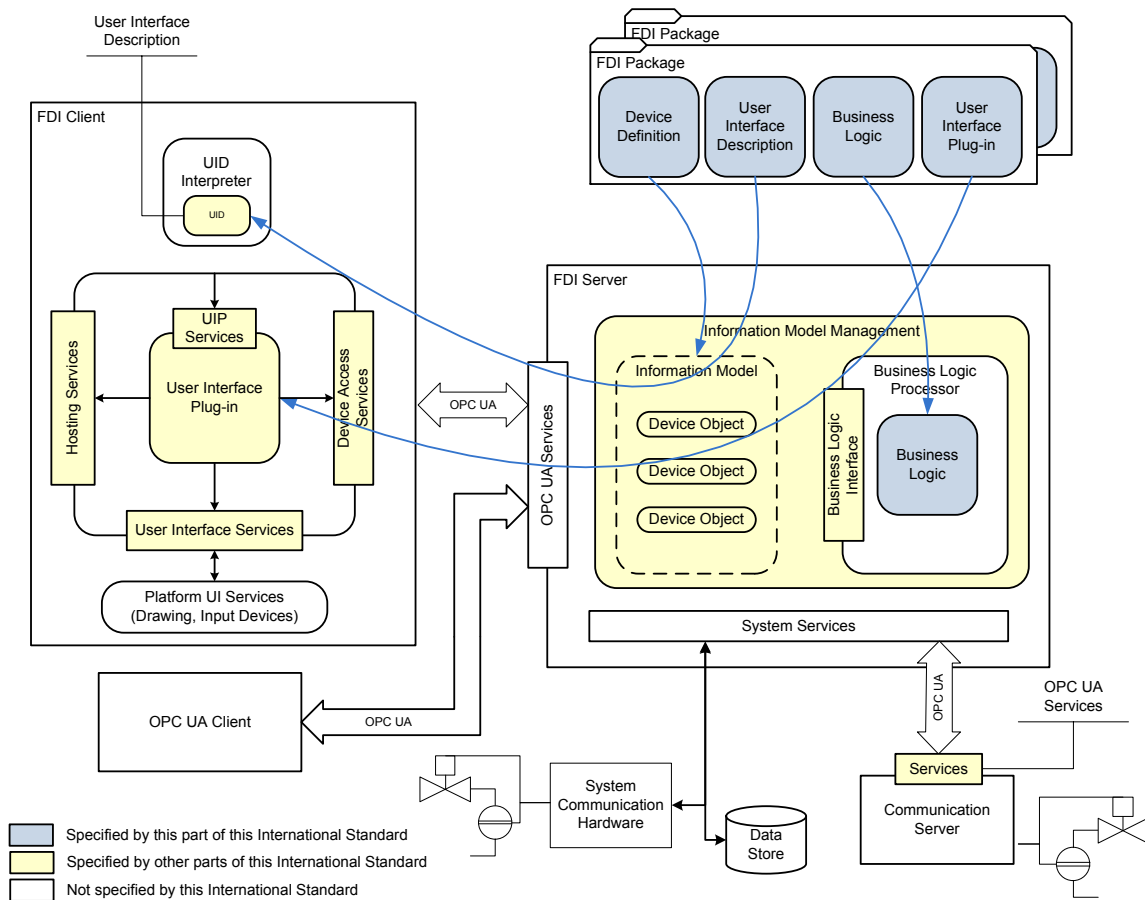


Figure 1 – FDI architecture diagram

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

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